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Vishay Semiconductors

## High Speed Infrared Emitting Diodes, 890 nm, GaAlAs, DH



#### DESCRIPTION

VSMF2893X01 series are infrared, 890 nm emitting diodes in GaAlAs (DH) technology with high radiant power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

#### FEATURES

- · Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.55
- AEC-Q101 qualified
- Peak wavelength:  $\lambda_p = 890 \text{ nm}$
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity:  $\phi = \pm 25^{\circ}$
- Low forward voltage
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reserve gullwing
- Package matches with detector VEMD2xx3X01 and VEMT2xx3X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### **APPLICATIONS**

- IrDA compatible data transmission
- 3D TV
- IR touch panels
- Miniature light barrier
- Photointerrupters
- Optical switch
- · Shaft encoders
- IR emitter source for proximity applications

#### **PRODUCT SUMMARY**

COMPONENT	l <sub>e</sub> (mW/sr)	φ (deg)	λ <sub>p</sub> (nm)	t <sub>r</sub> (ns)
VSMF2893RGX01	20	± 25	890	30
VSMF2893GX01	20	± 25	890	30

Note

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	PACKAGING REMARKS		
VSMF2893RGX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing	
VSMF2893GX01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing	

#### Note

MOQ: minimum order quantity

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(5-2008)



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ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V <sub>R</sub>	5	V	
Forward current		l <sub>F</sub>	100	mA	
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I <sub>FM</sub>	200	mA	
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	1	A	
Power dissipation		Pv	160	mW	
Junction temperature		Тj	100	°C	
Operating temperature range		T <sub>amb</sub>	- 40 to + 85	°C	
Storage temperature range		T <sub>stg</sub>	- 40 to + 100	°C	
Soldering temperature	Acc. figure 9, J-STD-020	T <sub>sd</sub>	260	°C	
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R <sub>thJA</sub>	250	K/W	

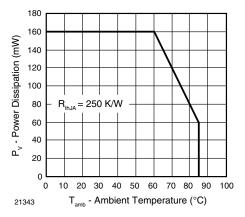


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

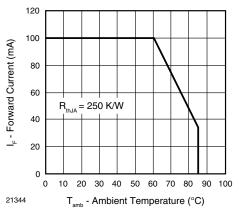


Fig. 2 - Forward Current Limit vs. Ambient Temperature

<b>BASIC CHARACTERSITICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	V <sub>F</sub>	1.25	1.4	1.6	V
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>		2.3		V
Temperature coefficient of $V_F$	I <sub>F</sub> = 1 mA	TK <sub>VF</sub>		- 1.8		mV/K
	l <sub>F</sub> = 100 mA	TK <sub>VF</sub>		- 1.1		mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>			10	μA
Junction capacitance	$V_{R} = 0 V, f = 1 MHz, E = 0 mW/cm^{2}$	CJ		125		pF
Radiant intensity	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	l <sub>e</sub>	10	20	30	mW/sr
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	l <sub>e</sub>		180		mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фе		40		mW
Temperature coefficient of $\phi_{\text{e}}$	l <sub>F</sub> = 100 mA	TKφ <sub>e</sub>		- 0.35		%/K
Angle of half intensity		φ		± 25		deg
Peak wavelength	I <sub>F</sub> = 30 mA	λp	870	890	910	nm
Spectral bandwidth	I <sub>F</sub> = 30 mA	Δλ		40		nm
Temperature coefficient of $\lambda_p$	I <sub>F</sub> = 30 mA	TKλp		0.25		nm/K
Rise time	I <sub>F</sub> = 100 mA, 20 % to 80 %	tr		30		ns
Fall time	I <sub>F</sub> = 100 mA, 20 % to 80 %	t <sub>f</sub>		30		ns
Cut-off frequency	$I_{DC} = 70 \text{ mA}, I_{AC} = 30 \text{ mA pp}$	f <sub>c</sub>		12		MHz



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### BASIC CHARACTERSITICS (T<sub>amb</sub> = 25 °C, unless otherwise specified)

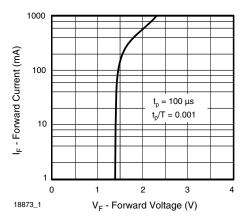


Fig. 3 - Forward Current vs. Forward Voltage

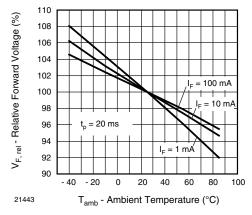


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

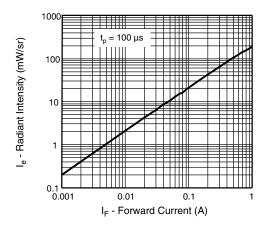


Fig. 5 - Radiant Intensity vs. Forward Current

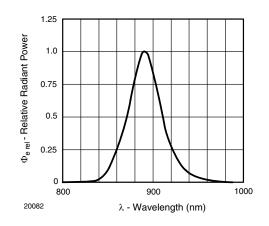


Fig. 6 - Relative Radiant Power vs. Wavelength

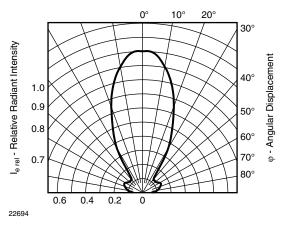


Fig. 7 - Relative Radiant Intensity vs. Angular Displacement

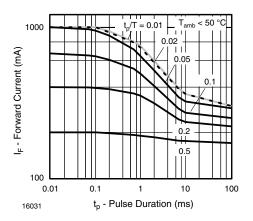


Fig. 8 - Pulse Forward Current vs. Pulse Duration

Rev. 1.0, 26-Feb-13

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For technical questions, contact: <u>emittertechsupport@vishay.com</u>

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#### SOLDER PROFILE

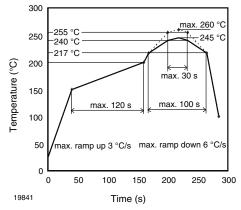


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

#### DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

#### FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions:  $T_{amb}$  < 30 °C, RH < 60 %

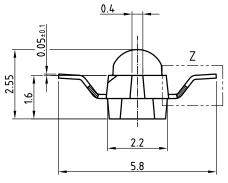
Moisture sensitivity level 2a, acc. to J-STD-020.

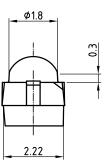
#### DRYING

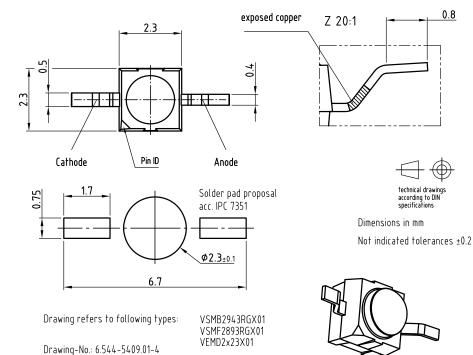
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

### PACKAGE DIMENSIONS in millimeters: VSMF2893RGX01

Issue: prel. 03.08.12







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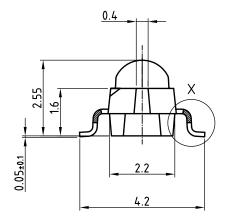
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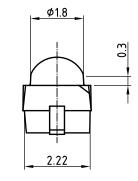
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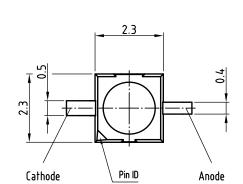


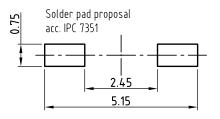
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#### PACKAGE DIMENSIONS in millimeters: VSMF2893GX01

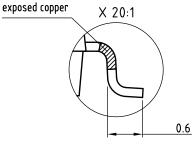






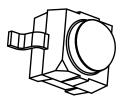


Drawing refers to following types: VSMB2943GX01 VSMF2893GX01 Drawing-No.: 6.544-5408.01-4 Issue: prel; 03.08.12





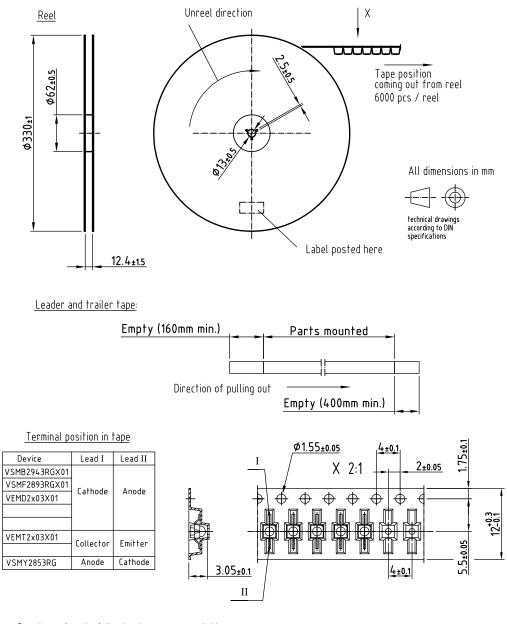
Dimensions in mm Not indicated tolerances ±0.2





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#### TAPING AND REEL DIMENSIONS in millimeters: VSMF2893RGX01



Drawing refers to following types: Reel dimensions and tape

see table

Drawing-No.: 9.800-5100.02-4 Issue: prel; 03.08.12

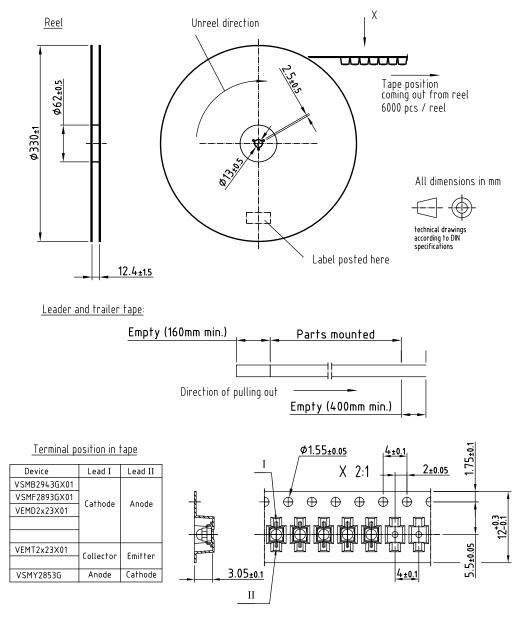
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#### TAPING AND REEL DIMENSIONS in millimeters: VSMF2893GX01



Drawing refers to following types: see table Reel dimensions and tape Drawing-No.: 9.800-5091.21-4 Issue: prel; 03.08.12



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